

# Die Bonder Equipment Market is Expected to Grow At a 4% CAGR to Reach US Dollars 6.0 Bn by 2032 | Future Market Insights

*Die Bonder Equipment Market is expected to reach US\$ 6.0 Billion in 2032, growing at a CAGR of 4% CAGR during 2022-2032 | Future Market Insights Inc.*

NEWARK, DELAWARE, UNITED STATES OF AMERICA, July 18, 2022 /EINPresswire.com/ -- Global [Die Bonder Equipment demand](#) is expected to be valued at US\$ 4.2 billion in 2022, rising at a CAGR of 4% to US\$ 6.0 billion from 2022 to 2032. Increased adoption of stacked die technology in Internet of Things (IoT) devices is driving growth.



Die Bonder Equipment

As a result, die bonder equipment is widely used in the fabrication of semiconductor devices. Furthermore, various methods, such as epoxy, eutectic, soft solder, and flip chip, are used to attach the die to the substrate.

This, in turn, is projected to create lucrative growth opportunities for the manufacturers of die boner equipment in the coming years owing to which the die bonder equipment market is also expected to grow at significant CAGR during the forecast period.

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## Global Die Bonder Equipment Market: Dynamics

Growing demand for semiconductor integrated circuits is one of the key factors expected to drive the overall demand for die bonder equipment in future. Increasing adoption of electronic systems due to rising number of end-use applications will create healthy demand for integrated circuits (ICs).

This, in turn, is propelling the demand for die bonder equipment in the global market.

Additionally, growing adoption of IOTs, ultra high definition television and hybrid laptops is further expected to create significant demand for die bonder equipment in future. Furthermore, growing demand for polymer adhesive water bonding equipment is further expected to become a barrier to the growth of the die bonder equipment market in future.

### Global Die Bonder Equipment Market: Regional Outlook

In the global market of die bonder equipment, Asia Pacific is expected to dominate the market owing to growing demand from the region. This growing demand can primarily be attributed to the presence of a huge number of IC manufacturers in the region. Growing IC demand due to increasing smartphones and tablets production will make the region grow at a healthy pace in future.

Moreover, the market for die bonder equipment in North America and Europe is also projected to grow at a healthy pace owing to increasing demand for semiconductors ICs from the region. The fast adoption of new and latest technologies in the region is also expected to drive the market in the region. Furthermore, MEA and Latin America are also expected to create demand for die bonder equipment in future as the market in these regions is in the growing stage as compared to other regions.

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### Global Die Bonder Equipment Market: Market Participants

In the global die bonder equipment market, manufacturers are continuously focused towards automation of the tie bonding technology. Names of some of the manufacturers engaged in the development and manufacturing of die bonder equipment are mentioned:

- Besi
- ASM Pacific Technology Limited (ASMPT)
- Kulicke & Soffa Industries, Inc.
- Tresky AG
- SHIBAURA MECHATRONICS CORPORATION
- West·Bond, Inc.
- Panasonic Corporation
- MRSI Systems
- SHINKAWA LTD.
- Palomar Technologies
- DIAS Automation
- Toray Engineering
- FASFORD TECHNOLOGY

The research report presents a comprehensive assessment of the Die Bonder Equipment market and contains thoughtful insights, facts, historical data, and statistically supported and industry-validated Die Bonder Equipment market data. It also contains projections using a suitable set of assumptions and methodologies. The research report provides analysis and information according to Die Bonder Equipment market segments such as geographies, application, and industry.

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## Global Die Bonder Equipment Market: Segmentation

The global die bonder equipment market can be segmented on the basis of product type, attachment method, end user and region.

On the basis of product type, the global market is segmented as:

- Manual Die Bonder Equipment
- Semi-Automatic Die Bonder Equipment
- Fully Automatic Die Bonder Equipment

On the basis of attachment method, the global market is segmented as:

- Epoxy Die Bonder
- Eutectic Die Bonder
- Soft Solder Die Bonder
- Flip Chip Die Bonder

On the basis of end user, the global market is segmented as:

- Integrated Device Manufacturers (DMs)
- Outsourced Semiconductor Assembly and Test (OSAT)

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- Sound Level Measurement Meter Market - Global sound level measurement meter demand is projected to be valued at US\$ 682 Million in 2022, forecast to grow at a CAGR of 5.1% to be valued at US\$ 1,120 Million from 2022 to 2032.
- Cold Forging Machines Market - Global Cold Forging Machines demand is projected to be valued at US\$ 22.16 Billion in 2022, forecast to grow at a CAGR of 5.5% to be valued at US\$ 38 Billion from 2022 to 2032.

- Electric Fireplace Market - The global electric fireplace market was worth US\$ 2.18 Billion in 2021, and is expected to register a Y-o-Y growth of 1.4%. The market is expected to grow at a CAGR of 3.7% between 2022 and 2032,
- Digital Instrument Clusters Market - The global digital instrument cluster market is estimated to exhibit growth at a robust CAGR over the forecast period 2022-2032.
- Variable Air Volume System Market - Total sales in the global variable air volume system market are projected to reach a valuation of nearly US\$ 12 Bn in 2022.

## About Us

Future Market Insights (ESOMAR certified market research organization and a member of Greater New York Chamber of Commerce) provides in-depth insights into governing factors elevating the demand in the market. It discloses opportunities that will favor the market growth in various segments on the basis of Source, Application, Sales Channel and End Use over the next 10-years.

## Contact:

Future Market Insights,

Unit No: 1602-006

Jumeirah Bay 2

Plot No: JLT-PH2-X2A

Jumeirah Lakes Towers

Dubai

United Arab Emirates

For Sales Enquiries: [sales@futuremarketinsights.com](mailto:sales@futuremarketinsights.com)

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Ankush Nikam

FMI

+91 90966 84197

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